



IECQ Certificate of Conformity

Capability

IECQ Certificate No.:	IECQ-C BSI 13.0001	Issue No.:	6	Status:	Current
Supersedes:	IECQ-C BSI 13.0001 Issue 5	Issue Date:	2024/01/31	Org Issue:	2013/02/06
CB Reference No.:	030/ICA	Expiration:	2027/01/31		

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The organization has developed and implemented procedures and related processes which have been assessed by the IECQ Certification Body issuing this certificate and found to comply with the applicable requirements of the IECQ Approved Component Scheme "Capability Certification" which is in accordance with the Basic Rules IECQ 01 "Rules of Procedure", IECQ 03-1 "IECQ General Requirements for all Schemes" and IECQ 03-3 Annex D "IECQ Approved Components Scheme" of the IEC Quality Assessment System for Electronic Component (IECQ), and in respect of standard(s) or specification(s):

- **IPC-6011 {July 1996}** Generic Performance Specification for Printed Boards
- **IPC-6012E {March 2020}** Qualification and Performance Specification for Rigid Printed Boards
- **IPC-6013D {September 2017}** Qualification and Performance Specification for Flexible/Rigid-Flexible Printed Boards

Process Manual Reference: **BS/IPC/CM01 IECQ 03-3 Annex D**

Details of Components/Assemblies/Materials:

Rigid Multilayer
Flex-Rigid multilayer with through holes
Rigid double-sided with plated through holes
Rigid single & double-sided with plain holes

-- Attached Schedule: 030_ICA scope Issue 6.pdf --

Issued by the Certification Body (CB): BSI

Kitemark Court, Davy Avenue
Knowlhill, Milton Keynes MK5 8PP
United Kingdom

Authorized person:
Shahm Barhom



The validity of this certificate is maintained through on-going surveillance audits by the IECQ CB issuing this certificate.
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Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 13.0001

CB Certificate No.: 030/ICA

Schedule Number: IECQ-C BSI 13.0001-S

Rev No.: 6

Revision Date: 2024/01/31

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Board Types:	Rigid Multilayer (Type 4)	IPC 6012E Class 3*
	Rigid double-sided with plated through holes (Type 2)	
	Rigid single & double-sided with plain holes (Types 1 & 2)	
	Double-Sided boards (Type 2)	
	Single-Sided Boards (Type 1 & 2)	
	Flex-Rigid multilayer with through holes (Type 4)	IPC 6013D Class 3*
Base Materials:	Epoxy Woven Glass (IPC 4101, IPC 4202, IPC 4203, BS 4584)	
	Polyimide film/polyester film (IPC 4204)	
	Polytetrafluorethylene (IPC 4103)	
Board Size:	495.30 mm x 419.10 mm single/double and multilayer	
	261.87 mm x 322.33 mm flex-rigid multilayer	
Number of Layers:	32 maximum	Rigid multilayer
	10 maximum	Flex-Rigid multilayer
Conductors:	0.10 mm (photomech) Tolerance -0.02 +0.03 mm	
Plated-through Hole Diameter:	0.20 mm	Minimum Finished hole size
	0.80 mm	Minimum Finished hole size
Aspect Ratio:	20 : 1	Maximum single and double sided
	16.0 : 1	Maximum multilayer
	2.27 : 1	Maximum flex-rigid multilayer

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Finishes: * Hot Air Solder Levelling
Immersion Silver
2.5µm Gold over Copper Edge Contacts
Liquid Photopolymer Solder Resist
Legend; UV or Oven Cured
Solder resist UV cured

Additional: Selective Electroplated Nickel / Gold (2.5 µm) on Copper
Selective Electroless Nickel / Gold (0.05 µm) on Copper
Immersion Silver, Organic Coating
Nema LI 1

* This finish meets the solderability requirements.

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